

HPI

TE Internal #: 1-1735446-1 PCB Mount Header, Vertical, Wire-to-Board, 11 Position, 2 mm [. 079 in] Centerline, Partially Shrouded, Tin, Through Hole - Solder, Signal, HPI

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Connectors > PCB Connectors > PCB Headers & Receptacles > AMP HPI 2.0 mm Headers



Connector System: Wire-to-Board

Number of Positions: 11

Number of Rows: 1

Centerline (Pitch): 2 mm [.079 in]

PCB Mount Orientation: Vertical

All AMP HPI 2.0 mm Headers (205)

Features

Product Type Features

Connector System

Header Type

Wire-to-Board

Partially Shrouded

Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
PCB Connector Assembly Type	PCB Mount Header
Configuration Features	
Connector Contact Load Condition	Fully Loaded
Number of Positions	11
Number of Rows	1
PCB Mount Orientation	Vertical
Electrical Characteristics	
Operating Voltage	250 VAC
Body Features	
Primary Product Color	Natural
Contact Features	
Contact Mating Area Length	3.35 mm[.131 in]

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Mating Square Post Dimension	.5 mm[.02 in]
PCB Contact Termination Area Plating Material Thickness	2.03 μm[79.92 μin]
Contact Layout	Inline
PCB Contact Termination Area Plating Material Finish	Bright
Contact Shape & Form	Square
Contact Mating Area Plating Material Finish	Bright
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Tin
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.5 mm[.02 in]
Termination Post & Tail Length	3.4 mm[.134 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Polarization
Mating Retention	With
PCB Mount Retention Type	Retention Solder Tails
Mating Retention Type	Locking
Connector Mounting Type	Board Mount
Mating Alignment	With
PCB Mount Alignment	Without
PCB Mount Retention	With
Housing Features	
Housing Material	Thermoplastic
Centerline (Pitch)	2 mm[.079 in]
Dimensions	
Connector Length	24 mm[.945 in]
Connector Height	6.07 mm[.239 in]
Connector Width	4.7 mm[.185 in]
PCB Thickness (Recommended)	1 – 1.6 mm[.039 – .063 in]

Mating Alignment Type	Polarization
Mating Retention	With
PCB Mount Retention Type	Retention Solder Tails
Mating Retention Type	Locking
Connector Mounting Type	Board Mount
Mating Alignment	With
PCB Mount Alignment	Without
PCB Mount Retention	With
Housing Features	
Housing Features Housing Material	Thermoplastic
	Thermoplastic 2 mm[.079 in]
Housing Material	
Housing Material Centerline (Pitch)	
Housing Material Centerline (Pitch) Dimensions	2 mm[.079 in]
Housing Material Centerline (Pitch) Dimensions Connector Length	2 mm[.079 in] 24 mm[.945 in]

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Usage Conditions

Operating Temperature Range	-25 – 85 °C[-13 – 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	200
Packaging Type	Bag
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2022

(223) Does not contain REACH SVHC

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Halogen Content

Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

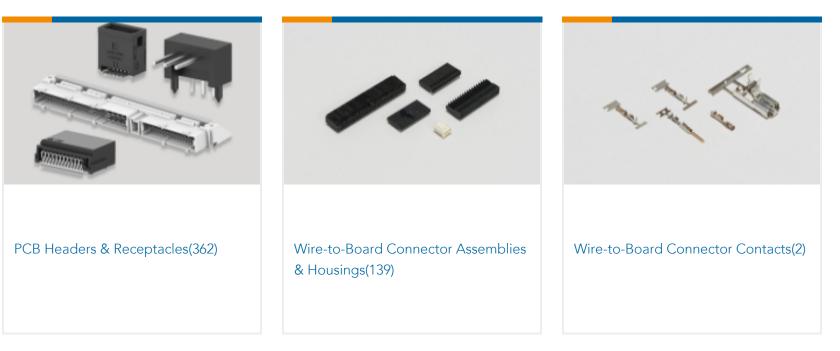
Compatible Parts

PCB Mount Header, Vertical, Wire-to-Board, 11 Position, 2 mm [.079 in] Centerline, Partially Shrouded, Tin, Through Hole - Solder, Signal, HPI





Also in the Series | HPI



Customers Also Bought





Documents

Product Drawings 2MM PITCH HPI POST HEADER, VERTICAL, 11P

English

CAD Files

Customer View Model

ENG_CVM_CVM_1-1735446-1_C.2d_dxf.zip

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English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1-1735446-1_C.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1-1735446-1_C.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages HPI Connectors QRG

English

Product Specifications Application Specification

English